

Layer Stack Legend

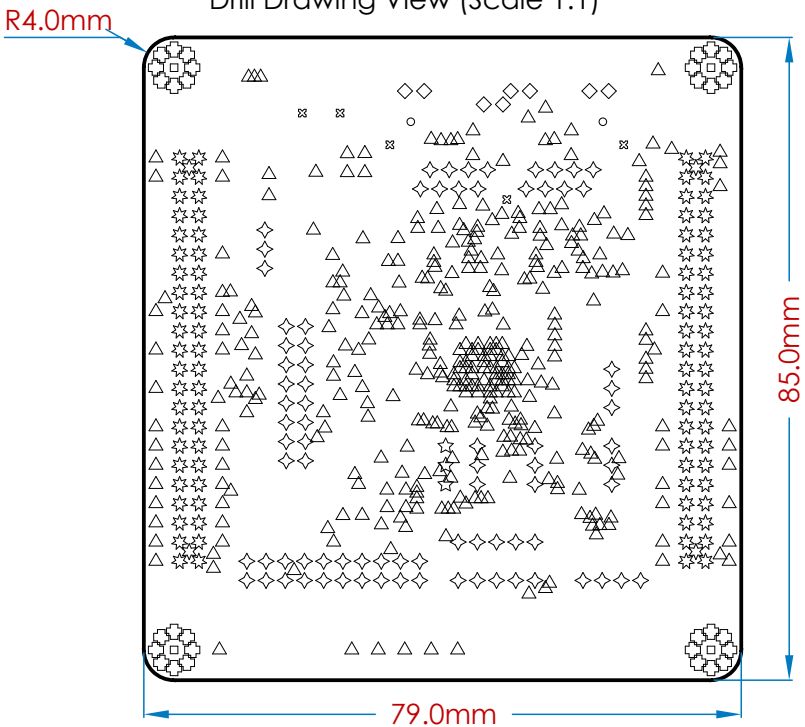
	Material	Layer	Thickness	Gerber
		Top Paste		GTP
		Top Overlay		GTO
	Surface Material	Top Soldermask	0.010mm	GTS
	Copper	Top Layer	0.035mm	GTL
	Prepreg		0.360mm	
	Copper	Mid1	0.036mm	G1
	Core		0.710mm	
	Copper	Mid2	0.036mm	G2
	Prepreg		0.360mm	
	Copper	Bottom Layer	0.035mm	GBL
	Surface Material	Bottom Soldermask	0.010mm	GBS
		Bottom Overlay		GBO
		Bottom Paste		GBP

Total thickness: 1.592mm

Notes:

- 1. Use current revision of all standards.
- 2. Board is to be manufactured in accordance to IPC-6012 Class 2.
- 3. Laminate (core) and prepreg to be in accordance with IPC-4101/126
- 4. Board finish shall be ENIG
- 5. Soldermask colour shall be WHITE
- 6. Silkscreen colour shall be BLACK
- 7. All hole dimensions apply after plating
- 8. All copper dimensions apply after plating

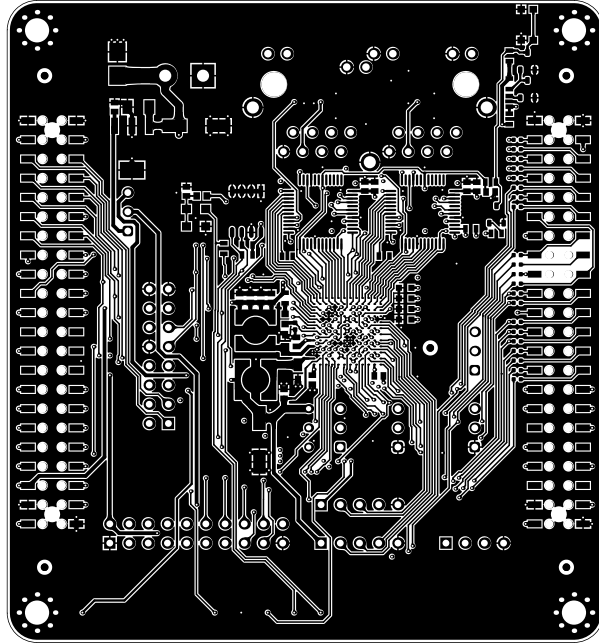
Drill Drawing View (Scale 1:1)



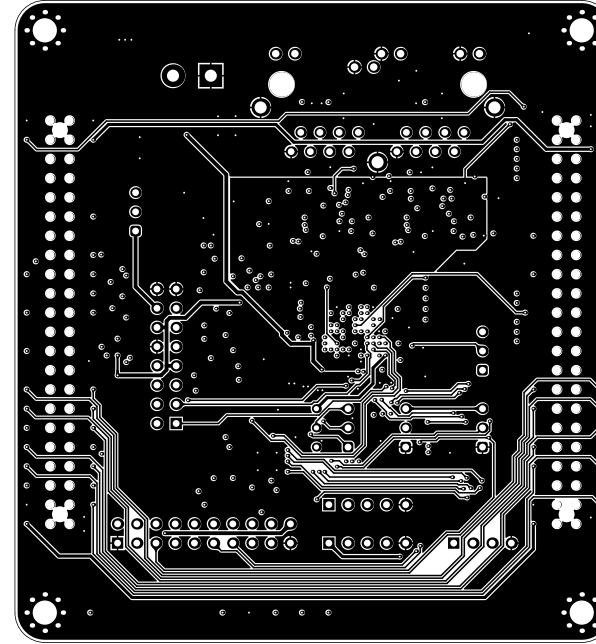
Drill Table

Symbol	Count	Hole Size	Plated	Via / Pad	Hole Tolerance
△	381	0.25	Plated	Via	None
⊠	32	0.60	Plated	Pad	None
☆	3	0.70	Plated	Pad	None
◇	81	0.90	Plated	Pad	None
◊	8	1.00	Plated	Pad	None
✧	88	1.10	Non-Plated	Pad	None
⊞	5	1.60	Plated	Pad	None
✧	4	1.80	Non-Plated	Pad	None
□	4	3.20	Plated	Pad	None
○	2	3.25	Non-Plated	Pad	None
	608 Total				

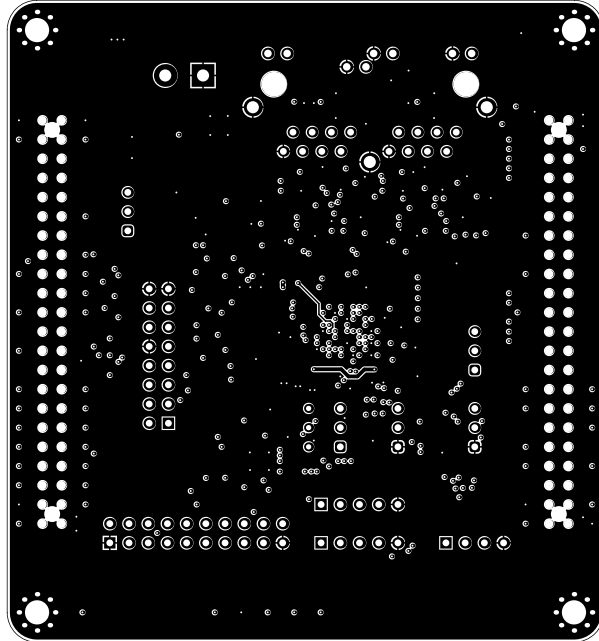
Top Layer (Scale 1:1)



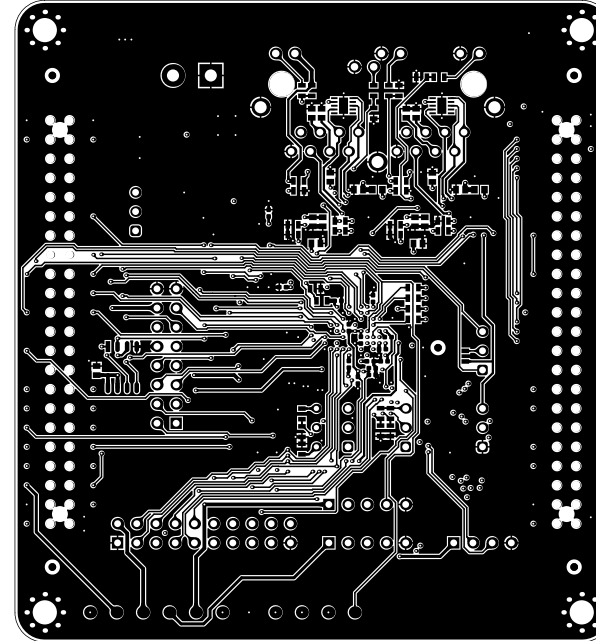
Mid1 (Scale 1:1)



Mid2 (Scale 1:1)

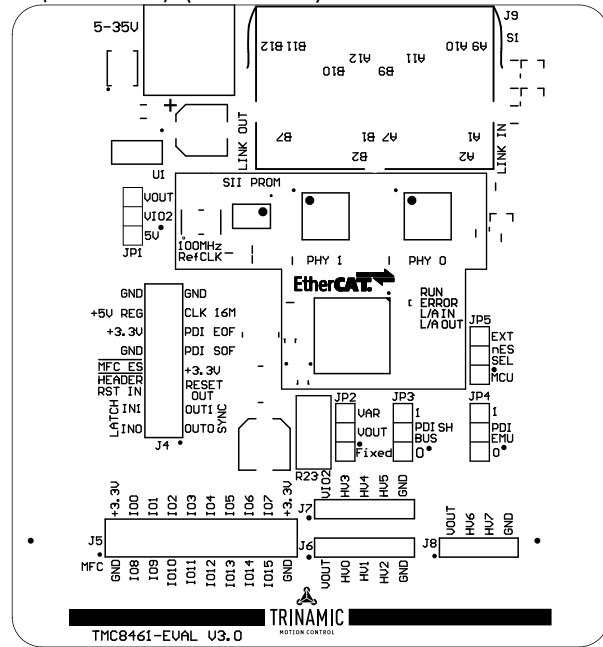


Bottom Layer (Scale 1:1)

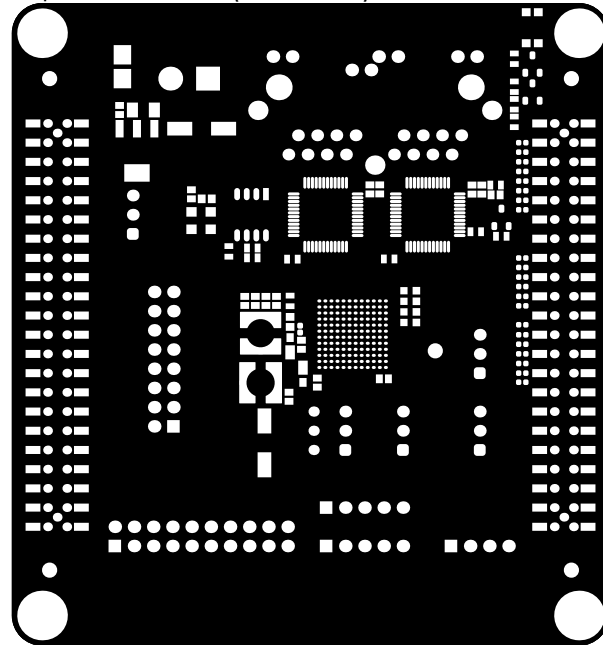


Title		
Fabrication Drawing		
Size	Revision	Project
A4	V3.0	TMC8461-EVAL
Date	7.03.2018 16:35	Sheet 2 of 4
File	TMC8461-EVAL-V3.0-F.PCBDwf	

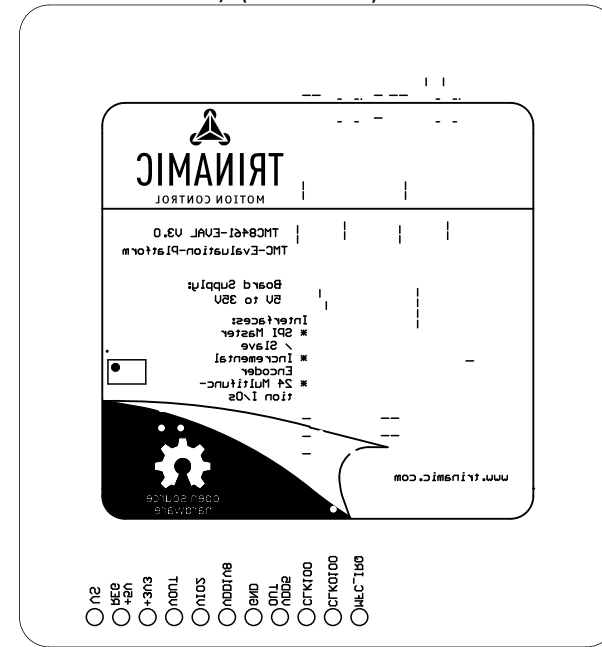
Top Overlay (Scale 1:1)



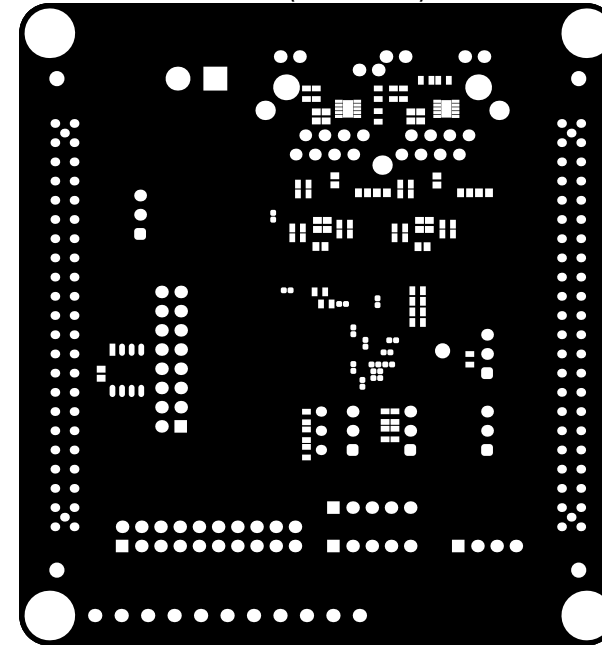
Top Soldermask (Scale 1:1)



Bottom Overlay (Scale 1:1)



Bottom Soldermask (Scale 1:1)

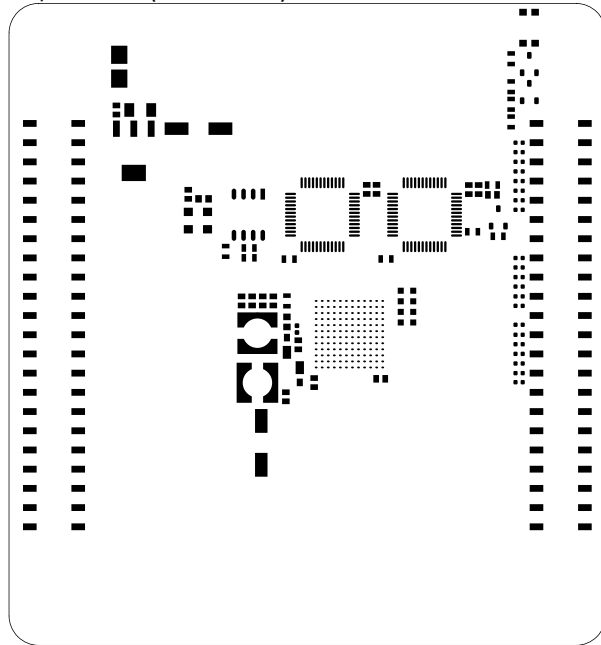


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Top Paste (Scale 1:1)



Bottom Paste (Scale 1:1)

